

Electronic Acknowledgement Receipt

EFS ID:	1280446
Application Number:	10789914
International Application Number:	
Confirmation Number:	8905
Title of Invention:	Resin composition, prepreg, laminate, and semiconductor package
First Named Inventor/Applicant Name:	Takeshi Hosomi
Customer Number:	27572
Filer:	Robert M. Siminski/Janice Ogg
Filer Authorized By:	Robert M. Siminski
Attorney Docket Number:	2497-000002/CP
Receipt Date:	30-OCT-2006
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Application Type:	Utility

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Submitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part /.zip	Pages (if appl.)
1	Response to Election / Restriction Filed	response_to_restriction.pdf	45703	no	2

Warnings:

Information:	
Total Files Size (in bytes):	45703
<p>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</p> <p><u>New Applications Under 35 U.S.C. 111</u> If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p><u>National Stage of an International Application under 35 U.S.C. 371</u> If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p>	